

ABSTRACT

A novel process for lapping a wafer is disclosed, which includes the steps of relieving adhesive stress of an ultraviolet tap attached to a first side of a wafer by irradiation of ultraviolet light, maintaining a lapping jig at a usable temperature of the ultraviolet tape to cause binder applied to the lapping jig to be melted, bonding the first side of the wafer to the lapping jig, and lapping the wafer. Thus, the present invention can provide a process capable of preventing damage to a wafer owing to deformation of an ultraviolet tape. The invention can also simplify an entire process to shorten the time required to complete the process and can minimize damage to a wafer by carrying out a lapping process using an ultraviolet tape as well as a grinding process capable of increasing etching amount of a wafer.